

General Description

The GreenMOS[®] high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.

The GreenMOS[®] Generic series is optimized for extreme switching performance to minimize switching loss. It is tailored for high power density applications to meet the highest efficiency standards.

Features

- Low $R_{DS(on)}$ & FOM
- Extremely low switching loss
- Excellent stability and uniformity




Applications

- PC power
- LED lighting
- Telecom power
- Server power
- EV Charger
- Solar/UPS

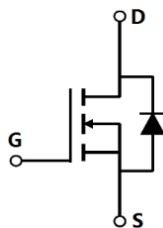
Key Performance Parameters

| Parameter | Value | Unit |
|-----------------------------------|-------|------------|
| V_{DS} | 900 | V |
| I_D , pulse | 18 | A |
| $R_{DS(ON)}$, max @ $V_{GS}=10V$ | 750 | m Ω |
| Q_g | 18.4 | nC |

Marking Information

| Product Name | Package | Marking |
|--------------|---------|------------|
| OSG90R750HF | TO247 | OSG90R750H |

Package & Pin Information



Absolute Maximum Ratings at $T_j=25^{\circ}\text{C}$ unless otherwise noted

| Parameter | Symbol | Value | Unit |
|---|----------------|------------|--------------------|
| Drain-source voltage | V_{DS} | 900 | V |
| Gate-source voltage | V_{GS} | ± 30 | V |
| Continuous drain current ¹⁾ , $T_C=25^{\circ}\text{C}$ | I_D | 6 | A |
| Continuous drain current ¹⁾ , $T_C=100^{\circ}\text{C}$ | | 3.8 | |
| Pulsed drain current ²⁾ , $T_C=25^{\circ}\text{C}$ | $I_{D, pulse}$ | 18 | A |
| Continuous diode forward current ¹⁾ , $T_C=25^{\circ}\text{C}$ | I_S | 6 | A |
| Diode pulsed current ²⁾ , $T_C=25^{\circ}\text{C}$ | $I_{S, pulse}$ | 18 | A |
| Power dissipation ³⁾ , $T_C=25^{\circ}\text{C}$ | P_D | 104 | W |
| Single pulsed avalanche energy ⁴⁾ | E_{AS} | 122 | mJ |
| MOSFET dv/dt ruggedness, $V_{DS}=0\dots 480\text{ V}$ | dv/dt | 50 | V/ns |
| Reverse diode dv/dt, $V_{DS}=0\dots 480\text{ V}$, $I_{SD}\leq I_D$ | dv/dt | 15 | V/ns |
| Operation and storage temperature | T_{stg}, T_j | -55 to 150 | $^{\circ}\text{C}$ |

Thermal Characteristics

| Parameter | Symbol | Value | Unit |
|--------------------------------------|-----------------|-------|----------------------|
| Thermal resistance, junction-case | $R_{\theta JC}$ | 1.2 | $^{\circ}\text{C/W}$ |
| Thermal resistance, junction-ambient | $R_{\theta JA}$ | 62 | $^{\circ}\text{C/W}$ |

Electrical Characteristics at $T_j=25^{\circ}\text{C}$ unless otherwise specified

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Test condition |
|----------------------------------|--------------|------|------|------|---------------|--|
| Drain-source breakdown voltage | BV_{DSS} | 950 | | | V | $V_{GS}=0\text{ V}$, $I_D=250\ \mu\text{A}$ |
| Gate threshold voltage | $V_{GS(th)}$ | 2.9 | | 3.9 | V | $V_{DS}=V_{GS}$, $I_D=250\ \mu\text{A}$ |
| Drain-source on-state resistance | $R_{DS(on)}$ | | 0.67 | 0.75 | Ω | $V_{GS}=10\text{ V}$, $I_D=3\text{ A}$ |
| | | | 1.98 | | | $V_{GS}=10\text{ V}$, $I_D=3\text{ A}$, $T_j=150^{\circ}\text{C}$ |
| Gate-source leakage current | I_{GSS} | | | 100 | nA | $V_{GS}=30\text{ V}$ |
| | | | | -100 | | $V_{GS}=-30\text{ V}$ |
| Drain-source leakage current | I_{DSS} | | | 1 | μA | $V_{DS}=900\text{ V}$, $V_{GS}=0\text{ V}$ |
| Gate resistance | R_G | | 21 | | Ω | $f=1\text{ MHz}$, Open drain |

Dynamic Characteristics

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Test condition |
|--|--------------|------|------|------|------|--|
| Input capacitance | C_{iss} | | 1250 | | pF | $V_{GS}=0\text{ V}$, $V_{DS}=50\text{ V}$, $f=100\text{ kHz}$ |
| Output capacitance | C_{oss} | | 49 | | pF | |
| Reverse transfer capacitance | C_{rss} | | 1.9 | | pF | |
| Effective output capacitance, energy related | $C_{o(er)}$ | | 29 | | pF | $V_{GS} = 0\text{ V}$, $V_{DS} = 0\text{V-}400\text{ V}$ |
| Effective output capacitance, time related | $C_{o(tr)}$ | | 133 | | pF | |
| Turn-on delay time | $t_{d(on)}$ | | 32.4 | | ns | $V_{GS}=10\text{ V}$, $V_{DS}=400\text{ V}$, $R_G=2\ \Omega$, $I_D=6\text{ A}$ |
| Rise time | t_r | | 19.8 | | ns | |
| Turn-off delay time | $t_{d(off)}$ | | 51.8 | | ns | |
| Fall time | t_f | | 14.2 | | ns | |

Gate Charge Characteristics

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Test condition |
|----------------------|---------------|------|------|------|------|---|
| Total gate charge | Q_g | | 18.4 | | nC | $V_{GS}=10\text{ V}$, $V_{DS}=400\text{ V}$, $I_D=6\text{ A}$ |
| Gate-source charge | Q_{gs} | | 6.2 | | nC | |
| Gate-drain charge | Q_{gd} | | 4.5 | | nC | |
| Gate plateau voltage | $V_{plateau}$ | | 5.5 | | V | |

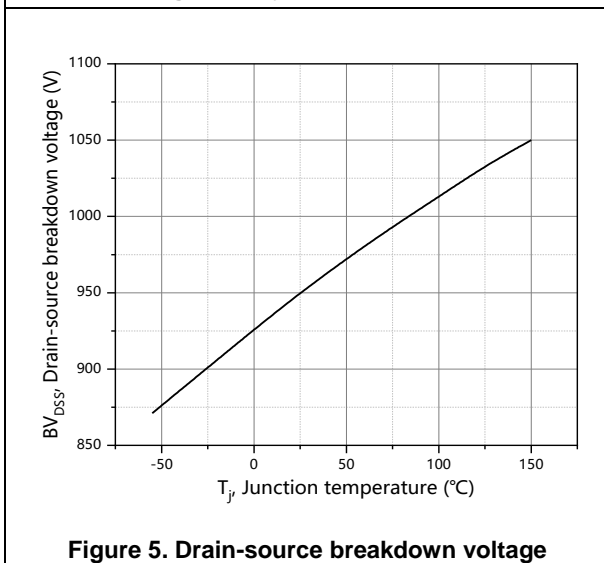
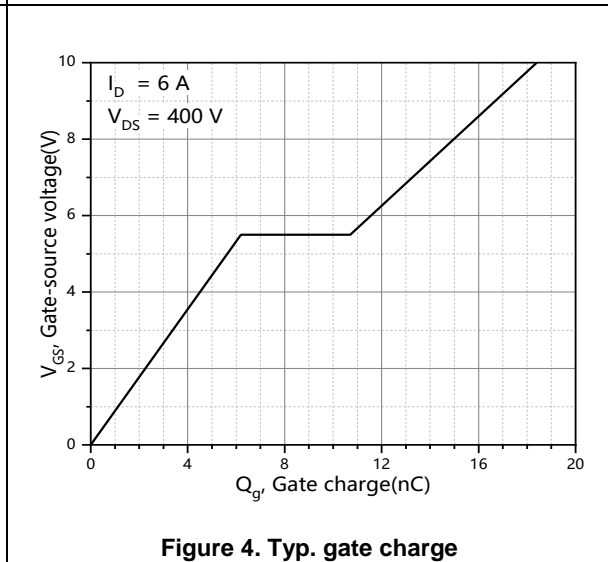
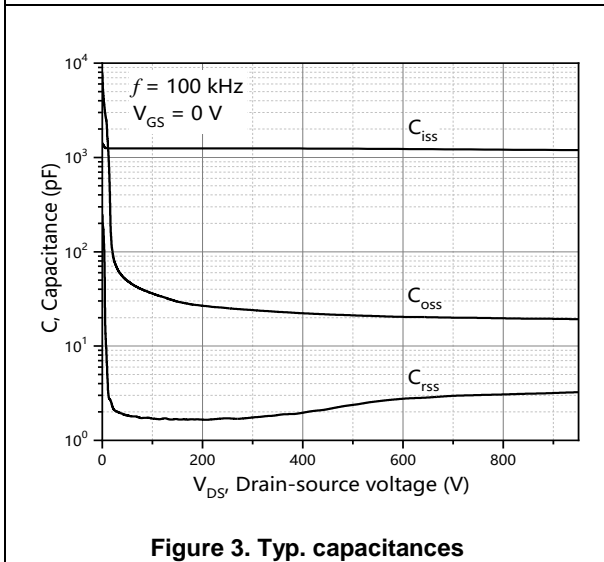
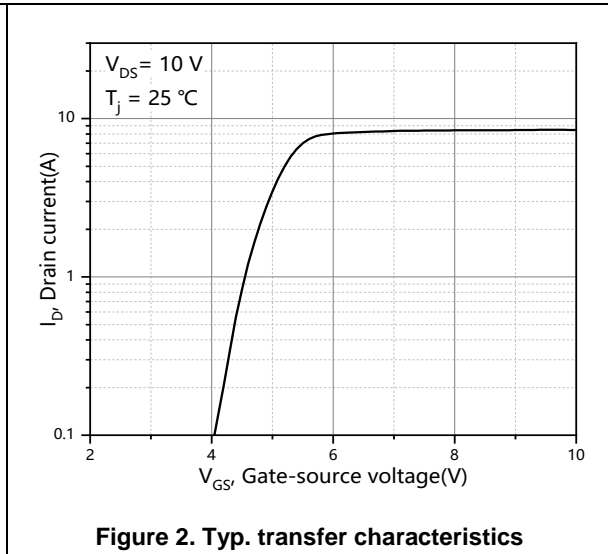
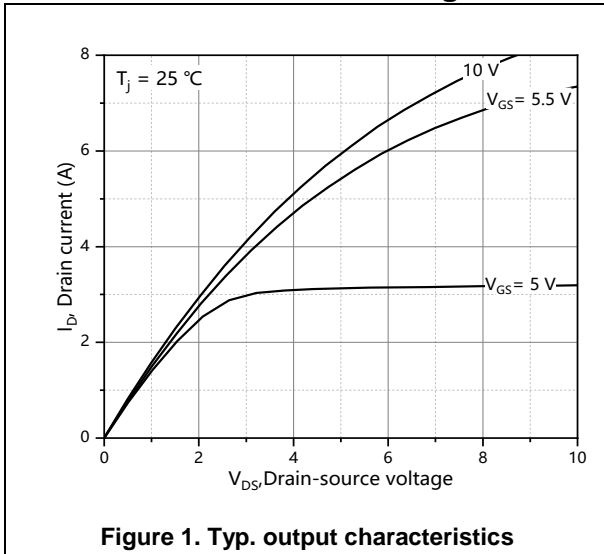
Body Diode Characteristics

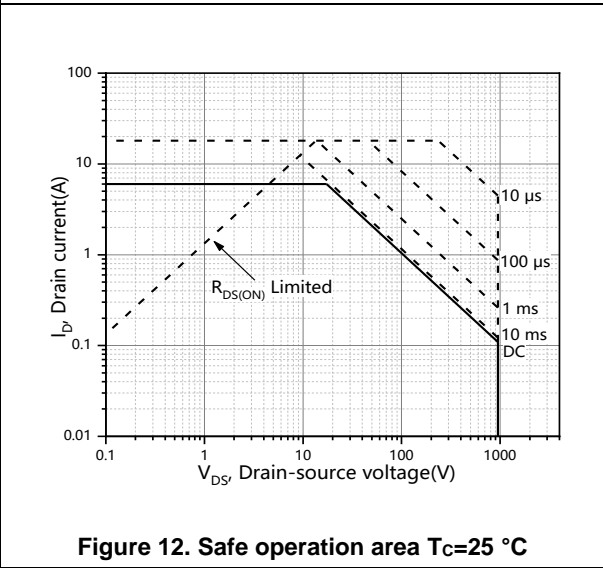
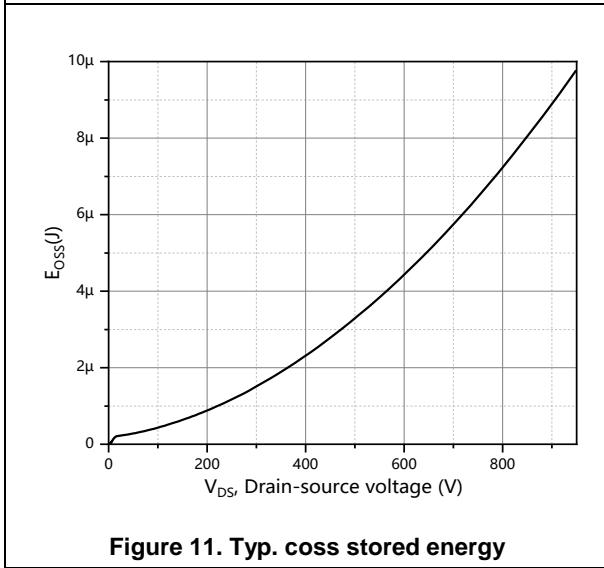
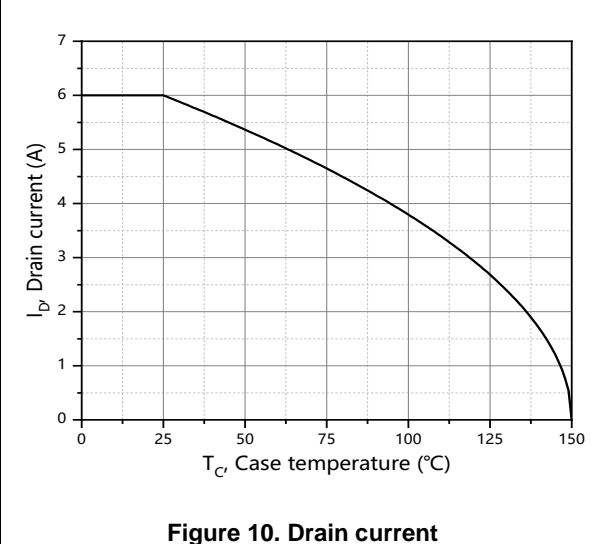
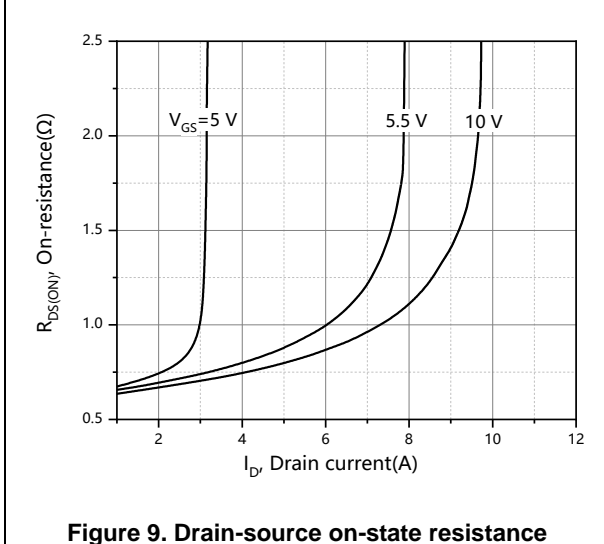
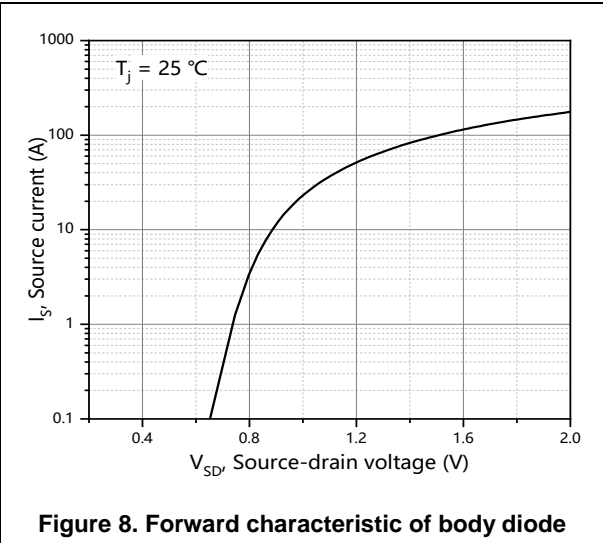
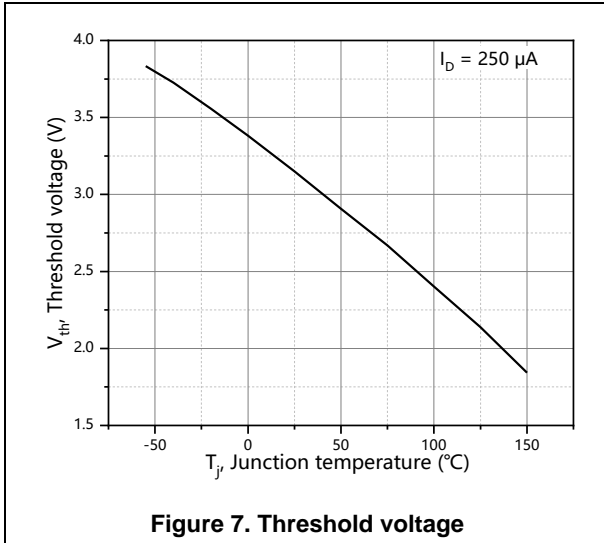
| Parameter | Symbol | Min. | Typ. | Max. | Unit | Test condition |
|-------------------------------|-----------|------|------|------|---------------|--|
| Diode forward voltage | V_{SD} | | | 1.3 | V | $I_S=6\text{ A}$, $V_{GS}=0\text{ V}$ |
| Reverse recovery time | t_{rr} | | 260 | | ns | $V_R=400\text{ V}$, $I_S=6\text{ A}$, $di/dt=100\text{ A}/\mu\text{s}$ |
| Reverse recovery charge | Q_{rr} | | 2.9 | | μC | |
| Peak reverse recovery current | I_{rrm} | | 18.7 | | A | |

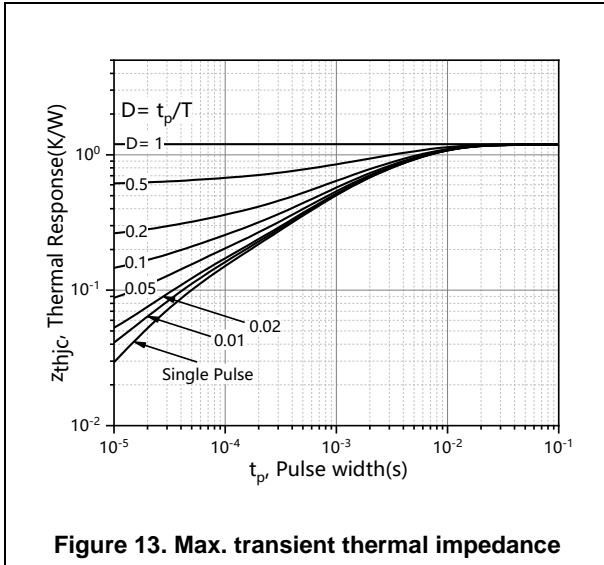
Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_d is based on max. junction temperature, using junction-case thermal resistance.
- 4) $V_{DD}=100\text{ V}$, $V_{GS}=10\text{ V}$, $L=80\text{ mH}$, starting $T_j=25\text{ }^\circ\text{C}$.

Electrical Characteristics Diagrams







Test circuits and waveforms

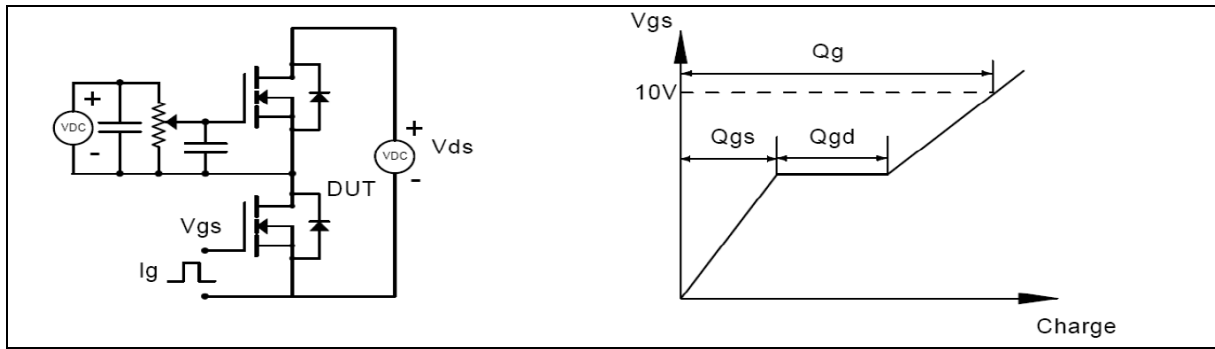


Figure 1. Gate charge test circuit & waveform

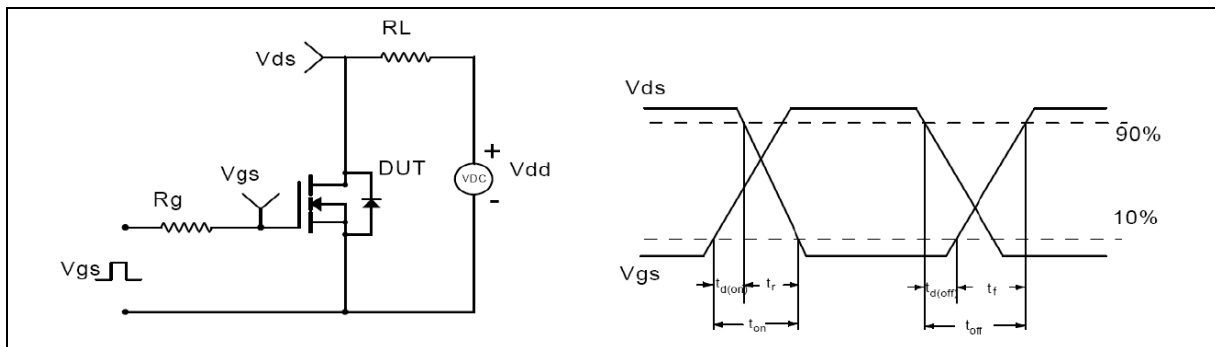


Figure 2. Switching time test circuit & waveforms

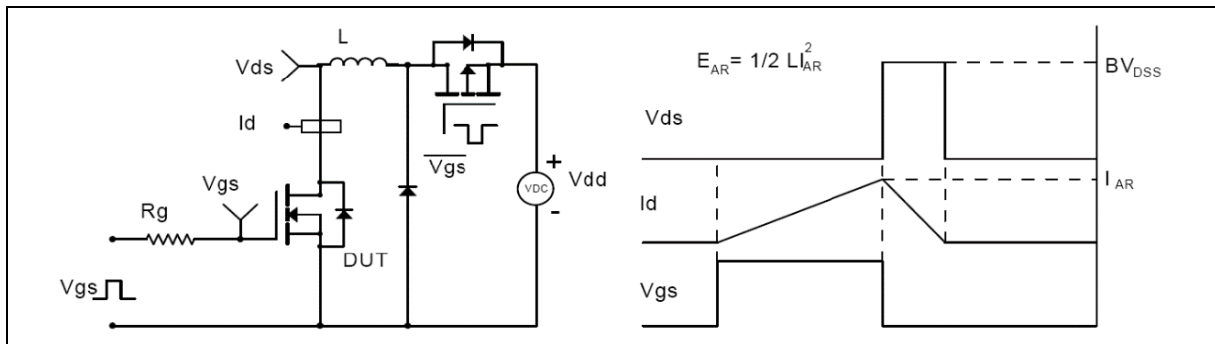


Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms

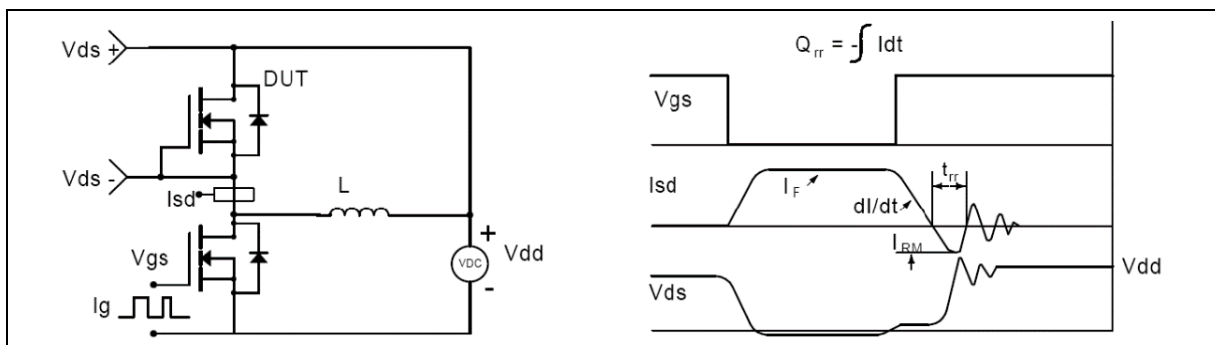
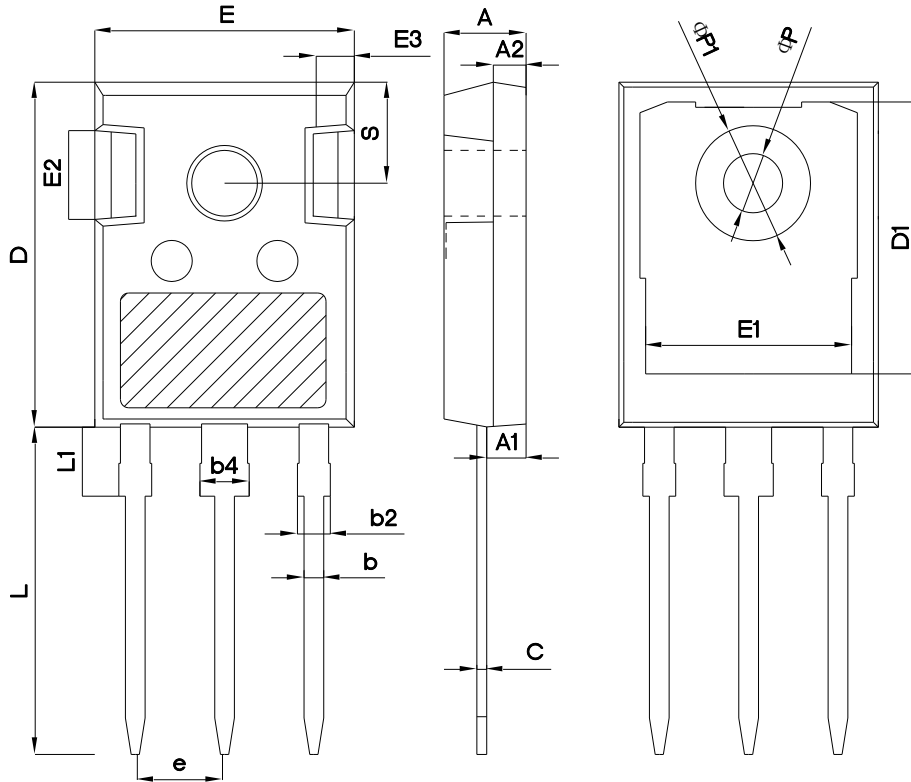


Figure 4. Diode reverse recovery test circuit & waveforms

Package Information



| Symbol | mm | | |
|--------|----------|-------|-------|
| | Min | Nom | Max |
| A | 4.80 | 5.00 | 5.20 |
| A1 | 2.21 | 2.41 | 2.59 |
| A2 | 1.85 | 2.00 | 2.15 |
| b | 1.11 | 1.21 | 1.36 |
| b2 | 1.91 | 2.01 | 2.21 |
| b4 | 2.91 | 3.01 | 3.21 |
| c | 0.51 | 0.61 | 0.75 |
| D | 20.80 | 21.00 | 21.30 |
| D1 | 16.25 | 16.55 | 16.85 |
| E | 15.50 | 15.80 | 16.10 |
| E1 | 13.00 | 13.30 | 13.60 |
| E2 | 4.80 | 5.00 | 5.20 |
| E3 | 2.30 | 2.50 | 2.70 |
| e | 5.44 BSC | | |
| L | 19.82 | 19.92 | 20.22 |
| L1 | - | - | 4.30 |
| ΦP | 3.40 | 3.60 | 3.80 |
| ΦP1 | - | - | 7.30 |
| S | 6.15 BSC | | |

Version: TO247-P package outline dimension

Ordering Information

| Package Type | Units/ Tube | Tubes / Inner Box | Units/ Inner Box | Inner Box/ Carton Box | Units/ Carton Box |
|--------------|-------------|-------------------|------------------|-----------------------|-------------------|
| TO247-P | 30 | 11 | 330 | 6 | 1980 |

Product Information

| Product | Package | Pb Free | RoHS | Halogen Free |
|-------------|---------|---------|------|--------------|
| OSG90R750HF | TO247 | yes | yes | yes |

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